



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Grigg et al.

Serial No.: 10/688,354

Filed: October 17, 2003

For: THICK SOLDER MASK FOR
CONFINING ENCAPSULANT MATERIAL
OVER SELECTED LOCATIONS OF A
SUBSTRATE AND ASSEMBLIES
INCLUDING THE SOLDER MASK

Confirmation No.: 2306

Examiner: C. Wilson

Group Art Unit: 2891

Attorney Docket No.: 2269-5216.1US
(99-0507.01/US)

Notice of Allowance Mailed:

January 3, 2006

NOTICE OF EXPRESS MAILING

Express Mail Mailing Label Number: EL995990072US

Date of Deposit with USPS: April 3, 2006

Person making Deposit: Timothy Palfreyman

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the specification begin on page 3 of this paper;

Amendments to the Abstract appear on page 7 of this paper;

Amendments to the claims are set forth in the listing of the claims that begins on page 8 of this paper;

Corrections to the drawings are summarized on page 11 of this paper, with replacement sheets and annotated sheets showing the corrections enclosed herewith; and

Remarks start at page 12 of this paper.